

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. – 10. (cancelled)

11. (currently amended) An apparatus comprising:

an electronic component body; and

one or more leads coupled to and extending from the electronic component body,

wherein a first lead of the one or more leads comprises a first leg and a second leg, the first leg and the second leg defining an acute angle therebetween,

wherein the second leg comprises a first portion defining the acute angle with the first leg, and a second portion substantially parallel to the first leg, and

wherein a length of the second portion that is substantially parallel to the first leg is substantially equal to a thickness of a substrate to which the electronic component body is to be mounted.

12. (cancelled)

13. (currently amended) An apparatus according to Claim ~~12~~11,

the second leg comprising a third portion defining an obtuse angle with the second portion.

14. (cancelled)

15. (currently amended) A method comprising:

bending an electronic component body lead to form a first leg and a second leg, the first leg and the second leg defining an acute angle therebetween; and

bending the second leg to form a first portion defining the acute angle with the first leg, and a second portion substantially parallel to the first leg,

wherein a length of the second portion that is substantially parallel to the first leg is substantially equal to a thickness of a substrate to which the electronic component body is to be mounted.

16. (cancelled)

17. (currently amended) A method according to Claim ~~16~~15, further comprising bending the second leg to form a third portion defining an obtuse angle with the second portion.

18. (cancelled)

19. (original) A method according to Claim 15, further comprising:
electrically coupling the lead to an electronic component body.

20. (original) A method according to Claim 15, wherein the lead is attached to an electronic component body.

21. (currently amended) A method comprising:
placing a lead of an electronic component body into an opening of a substrate, wherein the lead comprises a first leg and a second leg defining an acute angle therebetween,

wherein the second leg comprises a first portion defining the acute angle with the first leg, and a second portion substantially parallel to the first leg, and

wherein a length of the second portion that is substantially parallel to the first leg is substantially equal to a thickness of the substrate.

22. (cancelled)

23. (currently amended) A method according to Claim ~~22~~21, the second leg comprising a third portion defining an obtuse angle with the second portion.

24. (cancelled)

25. (original) A method according to Claim 21, further comprising:
electrically coupling the lead to the substrate.

26. (currently amended) An expansion card comprising:

a circuit board;

a connector coupled to the circuit board, the connector to connect to a motherboard; and

an electronic component body coupled to the circuit board, the electronic component body comprising one or more leads coupled to and extending from the electronic component body,

wherein a first lead of the one or more leads comprises a first leg and a second leg, the first leg and the second leg defining an acute angle therebetween,

wherein the second leg comprises a first portion defining the acute angle with the first leg, and a second portion substantially parallel to the first leg, and

wherein a length of the second portion that is substantially parallel to the first leg is substantially equal to a thickness of the circuit board.

27. (cancelled)

28. (currently amended) An expansion card according to Claim ~~27~~26,
the second leg comprising a third portion defining an obtuse angle with the second portion.

29. (cancelled)